FACE MOUNTED DEVICE ON SMALL MOUNT PAD

ABSTRACT OF THE DISCLOSURE

The invention is package that includes a Lead-On-Chip (LOC) type lead frame that has a small die mount pad (32). The active or circuit side semiconductor die (33) is attached to the under side of the die mount pad (32) with an adhesive (37), letting the entire back side (33a) of the semiconductor die (33) contact the encapsulating material (18)to provide better adhesion.

FIGURE 3